

JFP UV-810 Curing System



The machines which require minimal training to operate

MADE
IN FRANCE



UV Tape curing System



UV-810

- The JFP UV-810 curing system is a device to irradiate the ultraviolet (UV) wavelength of 365nm.
- It irradiates the UV to the UV curing tape used in the wafer process (dicing and back-grinding).
- UV irradiation is able to easily remove chip or wafer from the tape which had a strong adhesive.
- Low cost model with low flow Nitrogen purge for the small component.

Simple to Set up and operate

- UV curing Time
- UV lamp Status Indicator Leds

Compact

- Table Top Design
- Size 8"x10"
- Wafer on ring
- Wafer on frame

Safe ozone free

- Low Temperature
- UV-A 365 nm-A curing process
- Nitrogen Flow

Technical Specifications

Voltage: 100/ 230 VAC
Size: 320x350x120 mm
Weight: 4 kg